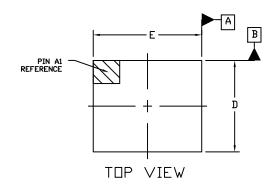


WLCSP8 1.39x1.65x0.40 CASE 567WK ISSUE B

DATE 29 AUG 2018



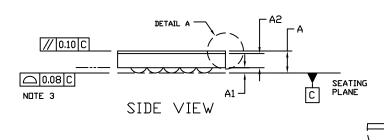
NOTES:

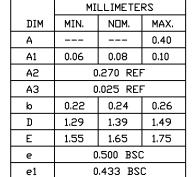
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- 6. BACKSIDE COATING IS OPTIONAL.

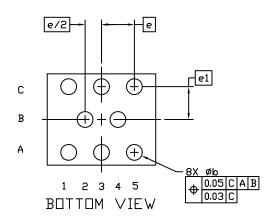
NOTE 6

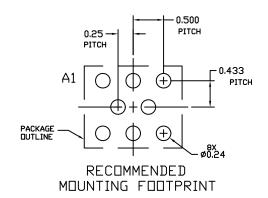
- A3

DETAIL A









GENERIC MARKING DIAGRAM*

XXX AYW XXX = Specific Device Code A = Assembly Location

Y = Year W = Work Week *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

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